

PART NO. : HFJT1-1G11RL



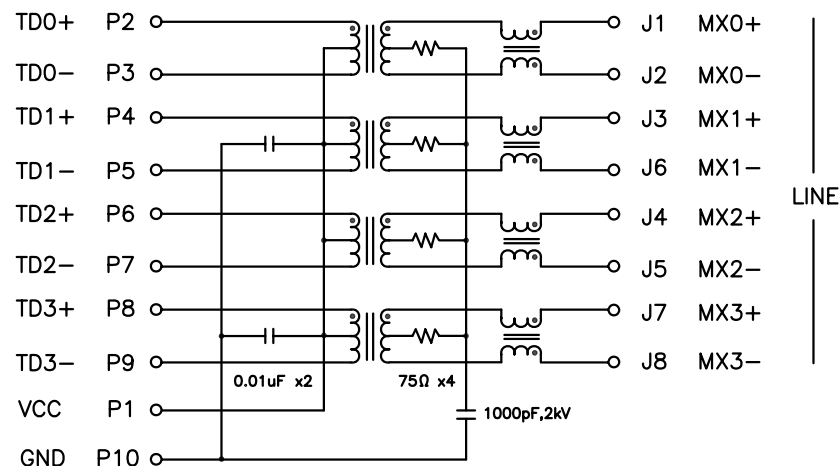
FASTJACK™ (TABUP) WITH 1000BASE-T MAGNETICS
 DESIGNED FOR IEEE802.3ab GIGABIT APPLICATIONS
 RoHS COMPLAINT

COMPATIBLE TO LEAD-FREE WAVE SOLDERING PROCESS
 FOR THROUGH HOLE COMPONENTS

OPERATING TEMPERATURE 0/70°C

ELECTRICAL SPECIFICATIONS @ 25° C

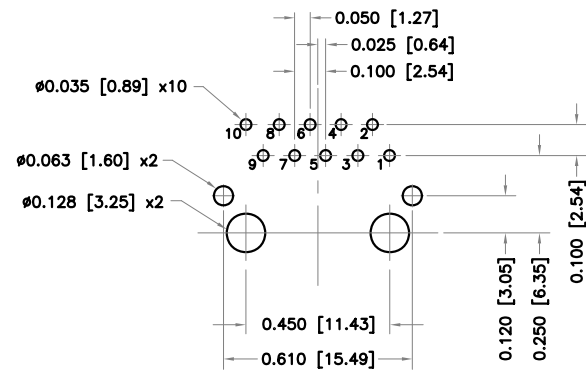
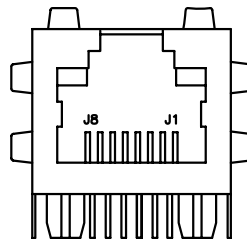
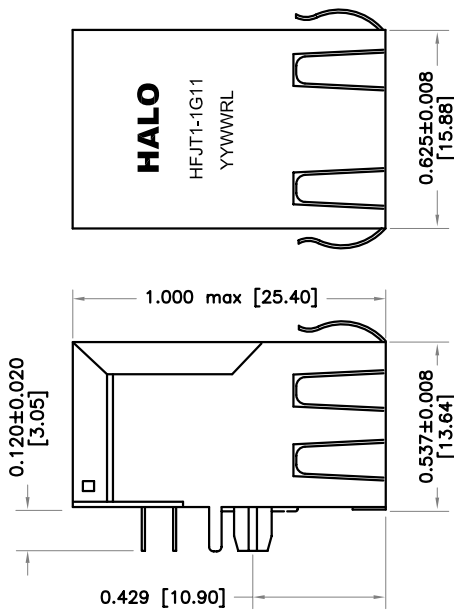
TURNS RATIO	1:1 ±3%
OCL (100KHz,0.1V,8mA)	350µH min
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK 1-100MHz	-35dB typ
CMR 0.1-30MHz	-50dB typ
30-60MHz	-40dB typ
60-100MHz	-35dB typ
ISOLATION	1,500Vrms



LINE



HALO/PBL	TITLE FastJack™ SINGLE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR GIGABIT ETHERNET		DRAWN LI ZHI ZHONG		10/20/05	A	FIRST ISSUE	10/20/05
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	PART NO. HFJT1-1G11RL		CHECKED LEI KEONG		4/13/11	B	PROD. RELEASE	4/13/11
	SCALE NONE	PAGE 1 OF 2	APPROVED PETER LU		4/13/11			
			FILE HFJT1-1G11RL.DWG					



Housing Material: Polyester, Black UL94V-0
 Contacts: Phosphor Bronze 30µm Au plating over Ni
 Leads: Matte Sn over Ni
 Shield: Cu Alloy with Ni plating 40µm min
 Durability: 1000 mating cycles
 Dimensions: Inch [mm]
 Tolerances: ±0.008 inch if not specified

RECOMMENDED P.C. BOARD PATTERN (COMP. SIDE)

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